PC/ LED/ IC 自動化設備
解決方案

萬潤科技簡介

Presented by Allring

關於我們

創立時間

May 24. 1996

董事長

Larry Lu

資本額

833 Million

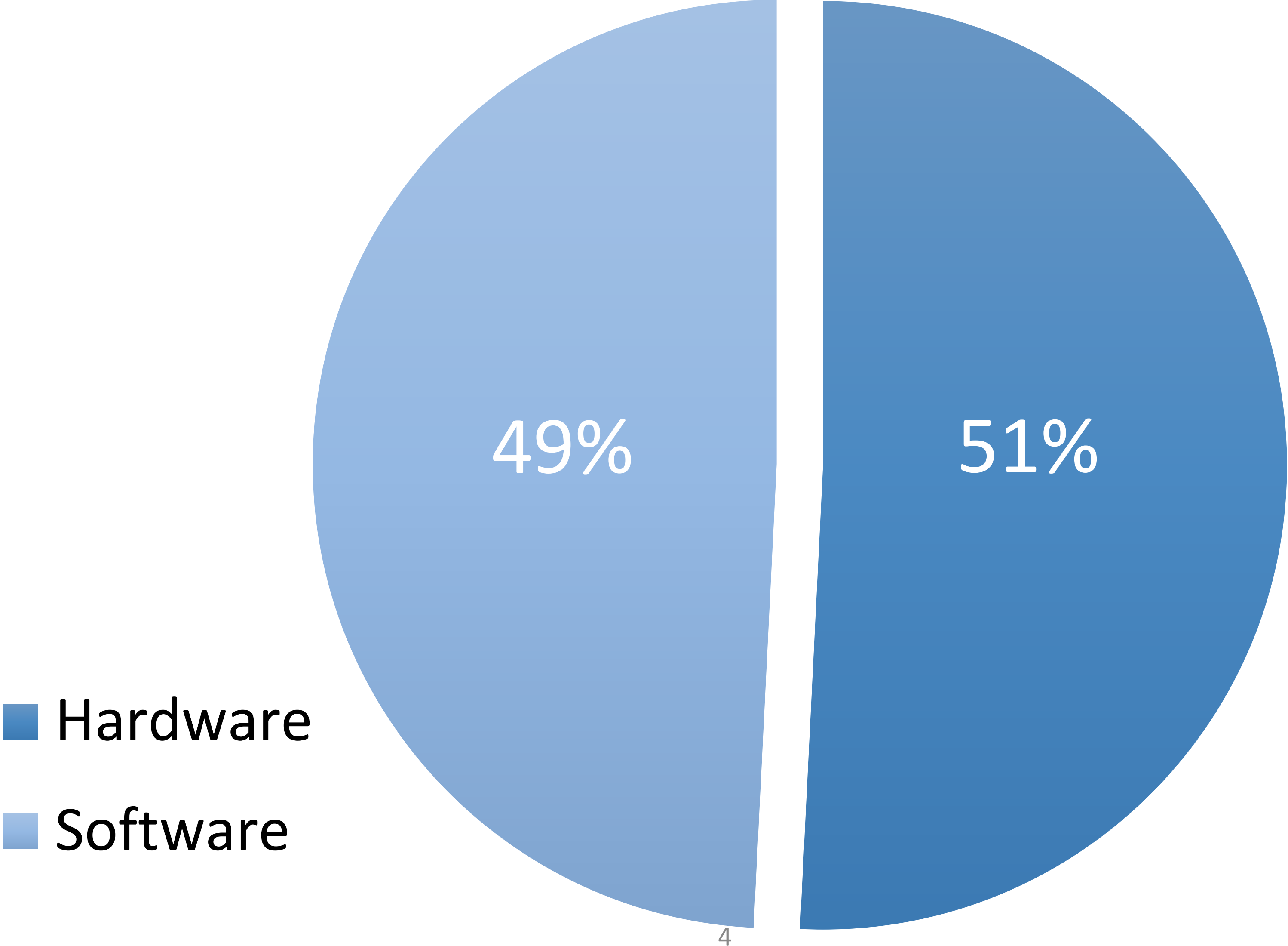
主要業務

專注於半導體、被動元件及LED製程之自動化機械設備

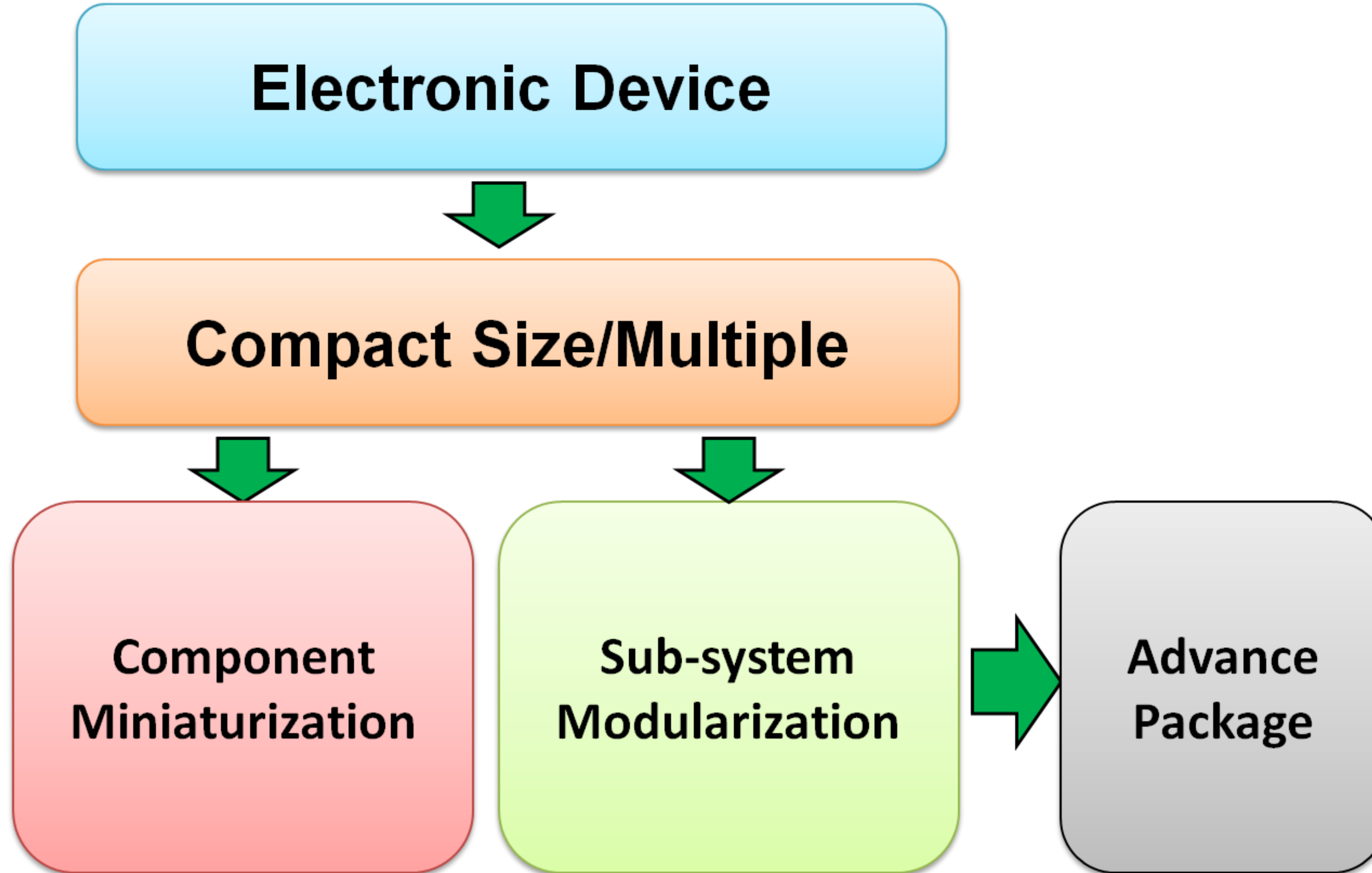
60%

研 發 人 員 在 整 體 公 司 員 工 數 的 占 比

集團人力資源分佈



產業概況



先進封裝

<table>
<tr><th colspan="2">Packaging Type</th><th colspan="2">Manufacturer</th><th>Application</th></tr>
<tr><td colspan="2" rowspan="6">SIP
(system in package)</td><td rowspan="2">OSAT</td><td>ASE</td><td rowspan="6">Smart phone
IoT
Mobile</td></tr>
<tr><td>USI</td></tr>
<tr><td rowspan="2">Module house</td><td>Hon Hai</td></tr>
<tr><td>Luxshare</td></tr>
<tr><td rowspan="2">Component</td><td>AAC</td></tr>
<tr><td>AMS</td></tr>
<tr><td rowspan="2">3D Package</td><td>InFO,CoWoS</td><td rowspan="2">Foundry</td><td>TSMC</td><td rowspan="2">Smart Phone
IoT
Mobile</td></tr>
<tr><td>SoIC</td><td>TSMC</td></tr>
<tr><td rowspan="5">Flip chip</td><td rowspan="5">2D/2.5D</td><td rowspan="5">OSAT</td><td>ASE</td><td rowspan="5">Smart Phone
IoT
Mobile</td></tr>
<tr><td>Spil</td></tr>
<tr><td>Amkor</td></tr>
<tr><td>Chipbond</td></tr>
<tr><td>Powertech</td></tr>
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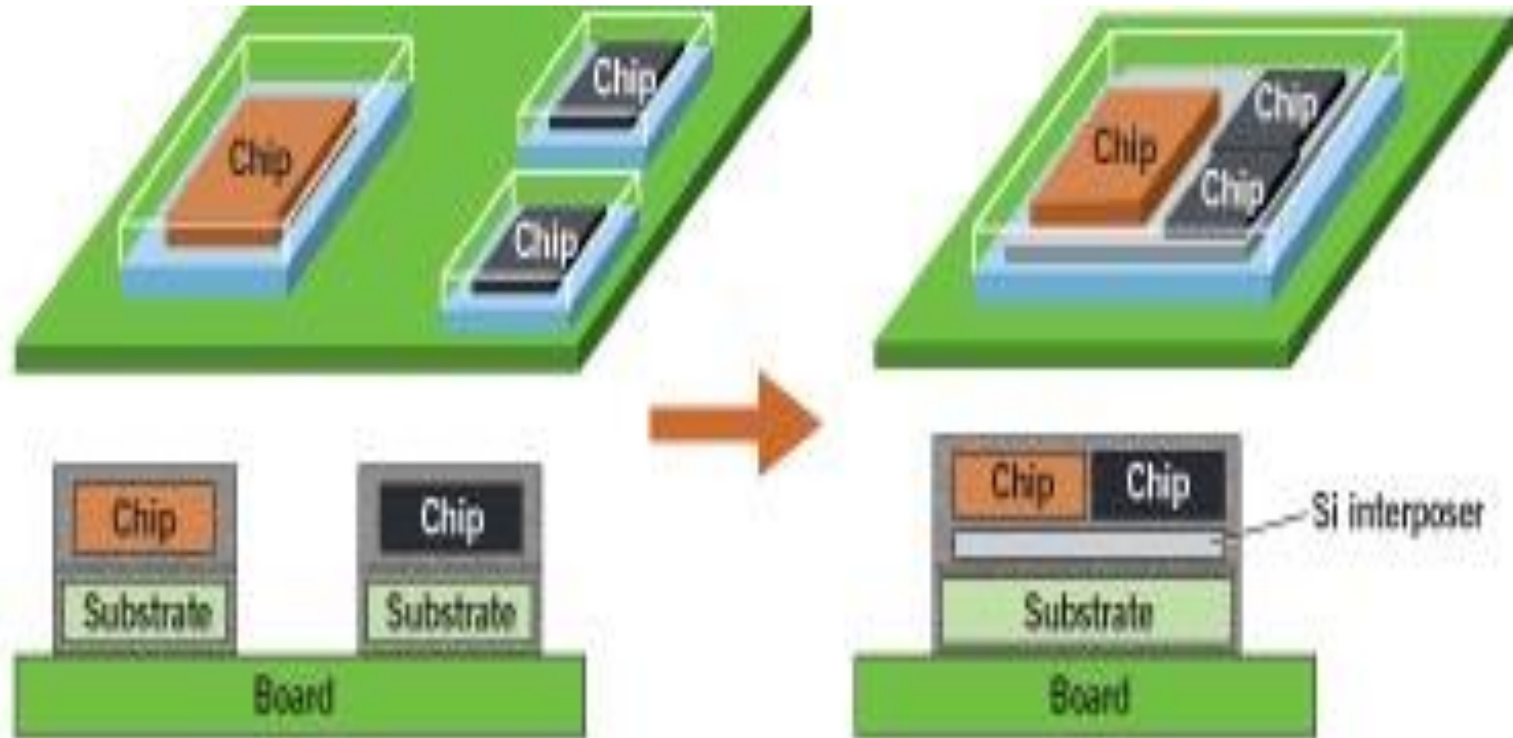
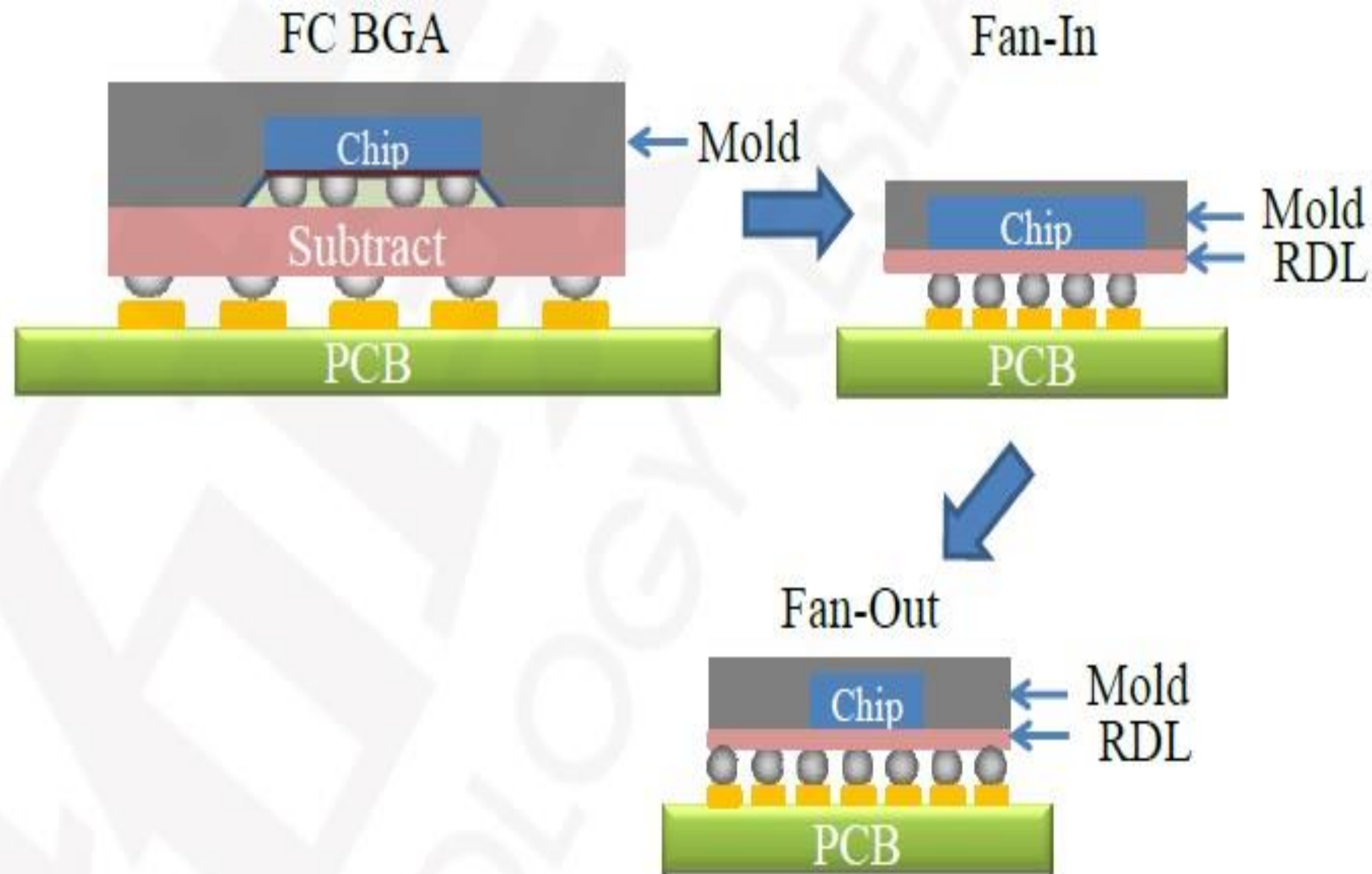
System in Package (SiP)

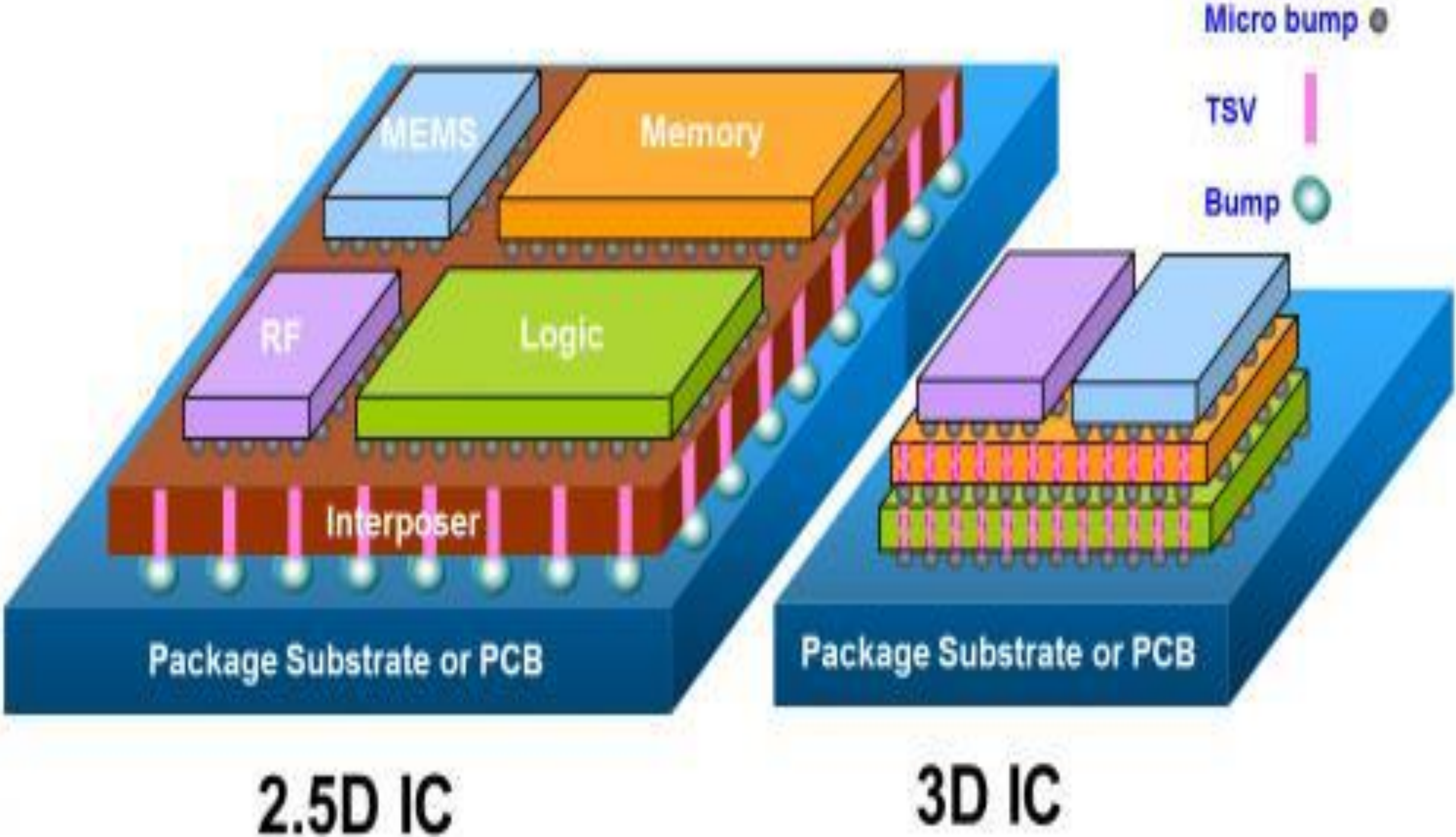


Flip-chip & wafer-level packaging

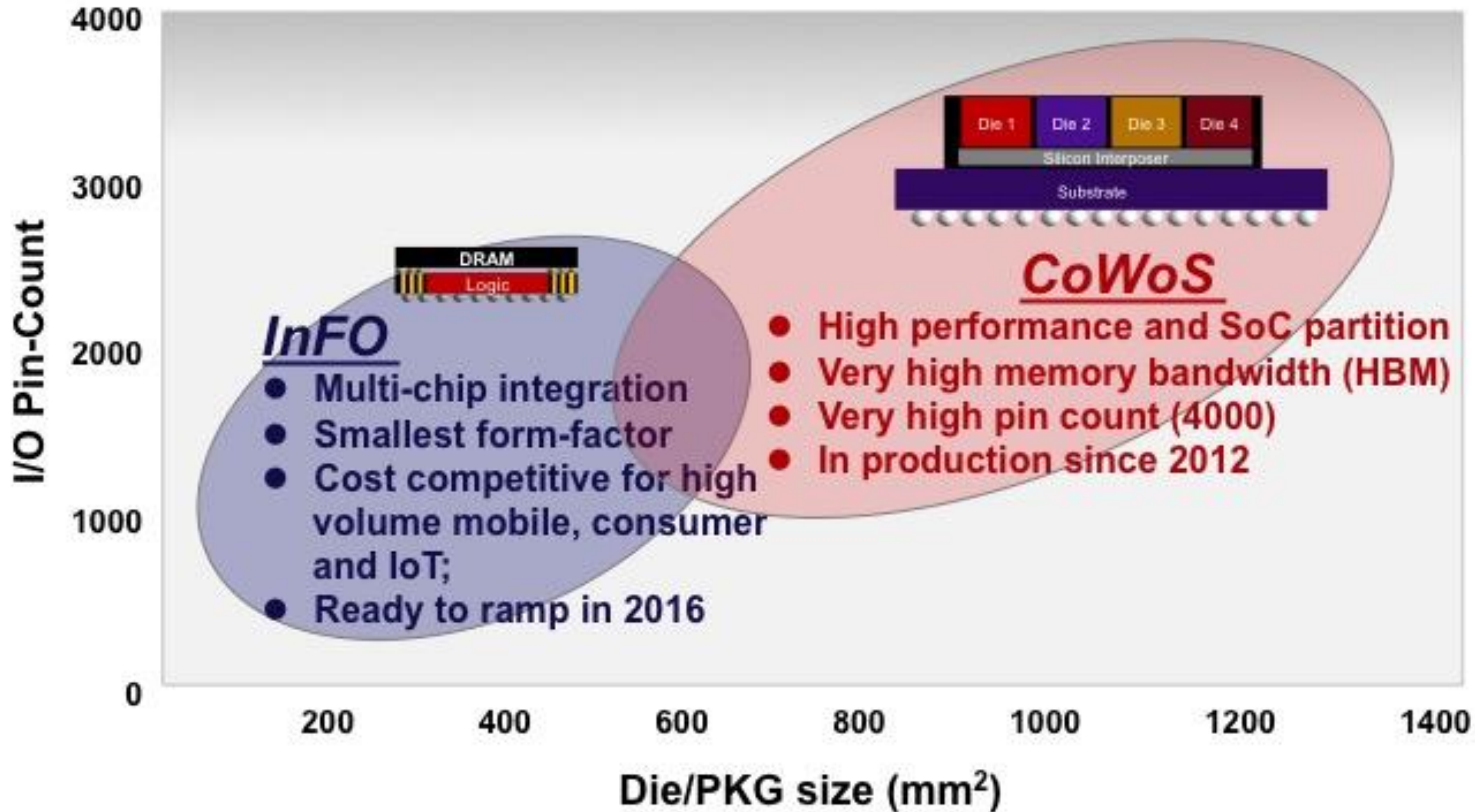


Source: TRI

2.5D & 3D IC Packaging



TSMC's InFO & CoWoS

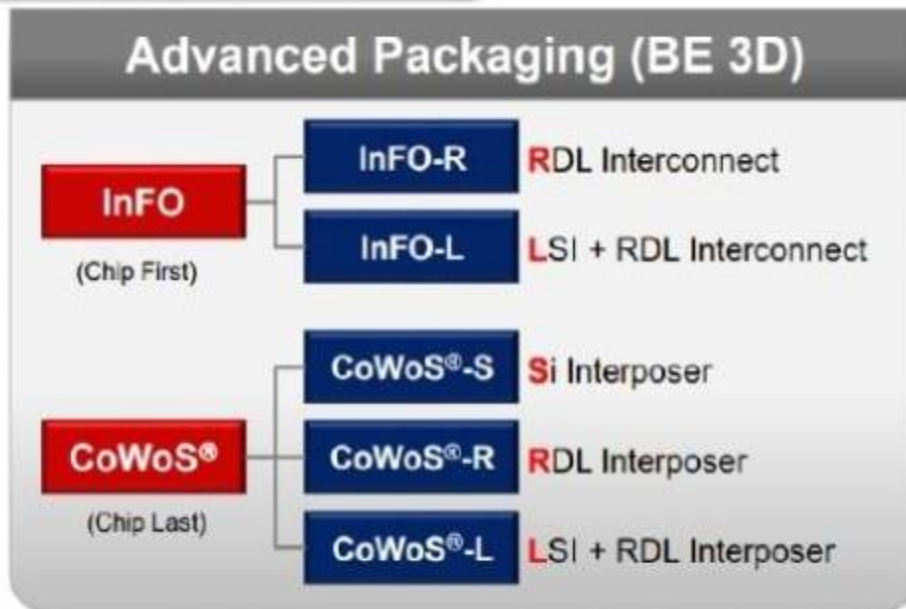


Source: TSMC

PUBLIC
Allring All Ring Tech Co., Ltd.

TSMC's 3D Fabric

TSMC 3DFabric™

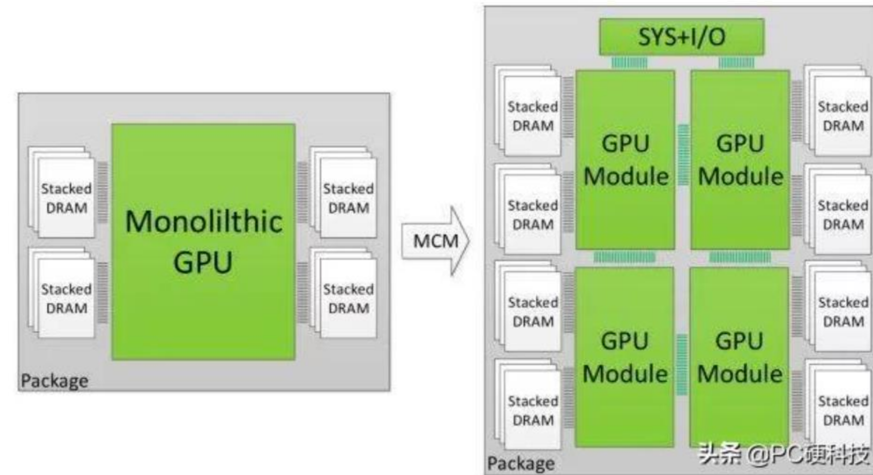


SoIC: System on Integrated Chips

InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

先進封裝

- Advanced packaging process
  - High Performance 2D with SoC & SoIC
    - Flip Chip – MCM(SiP)
    - （Multi-chip module；MCM）
  - 2.5D with SoC
    - COWOS
    - INFO
  - 3D with (SoIC & WoW)
    - COWOS
    - INFO



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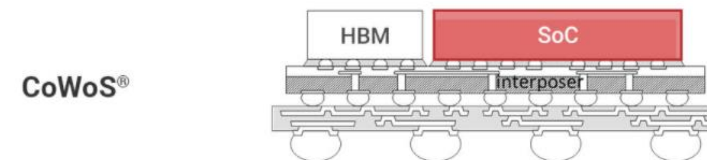

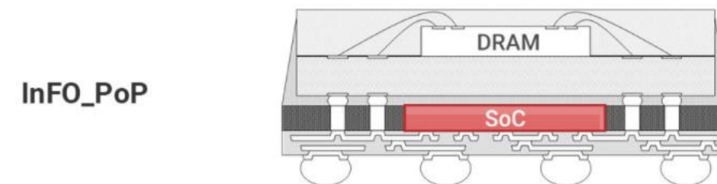

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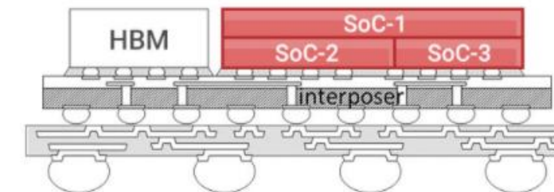

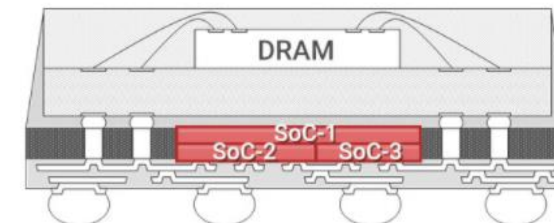

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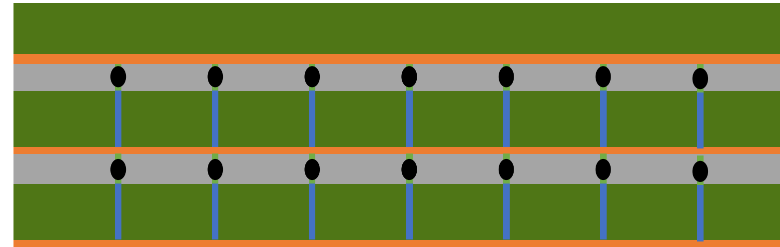
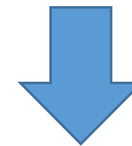
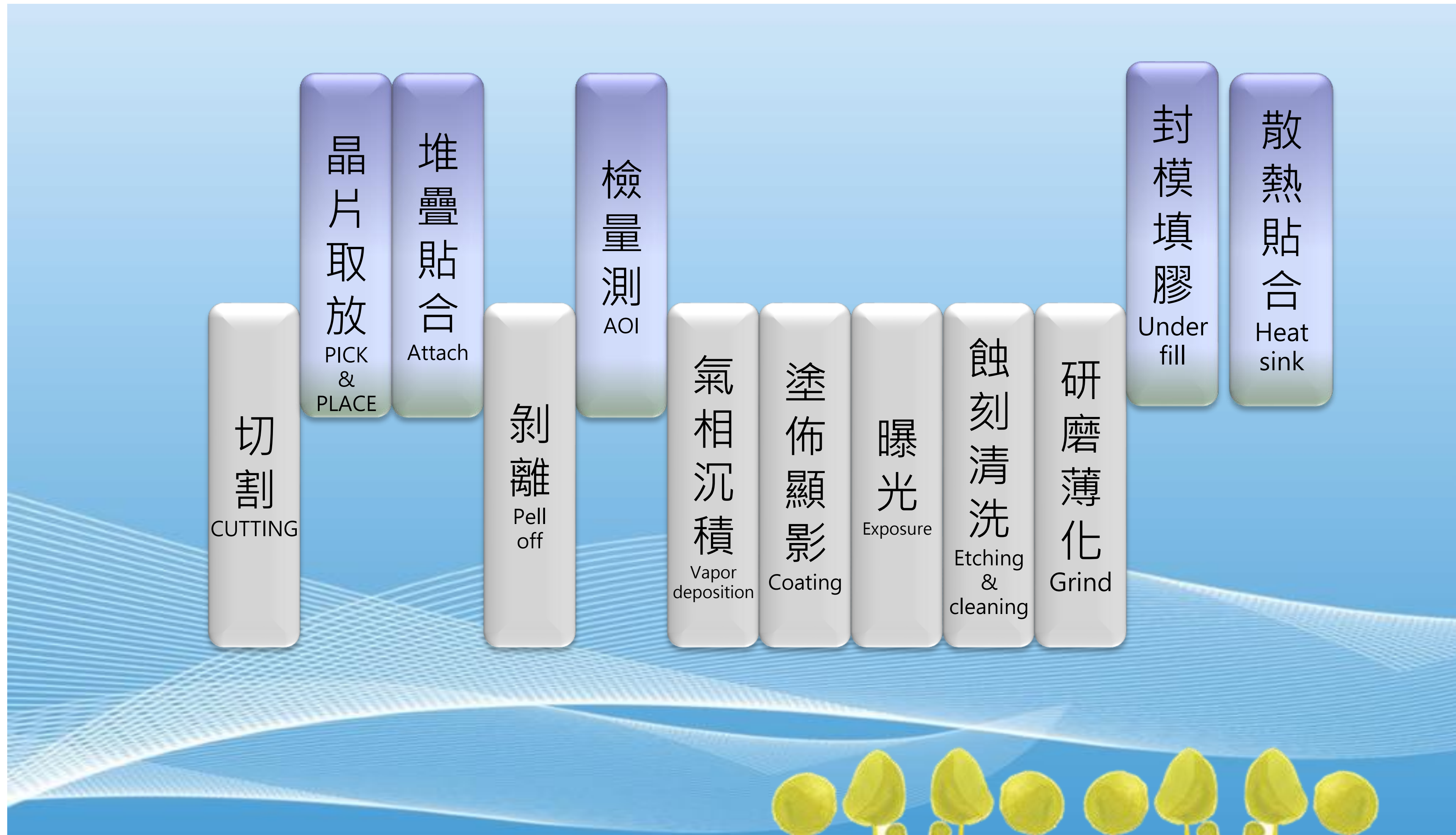
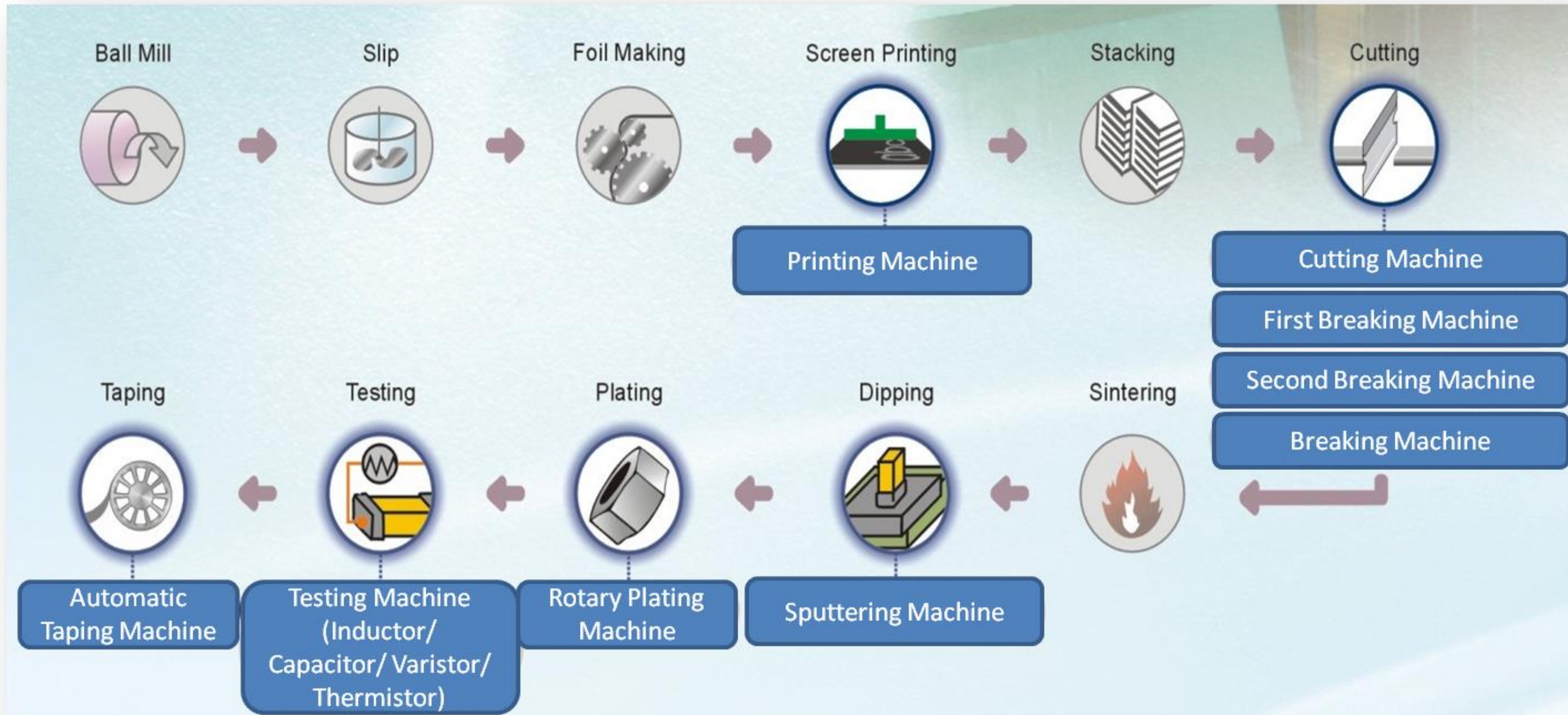




Allring in 3D Fabric Process



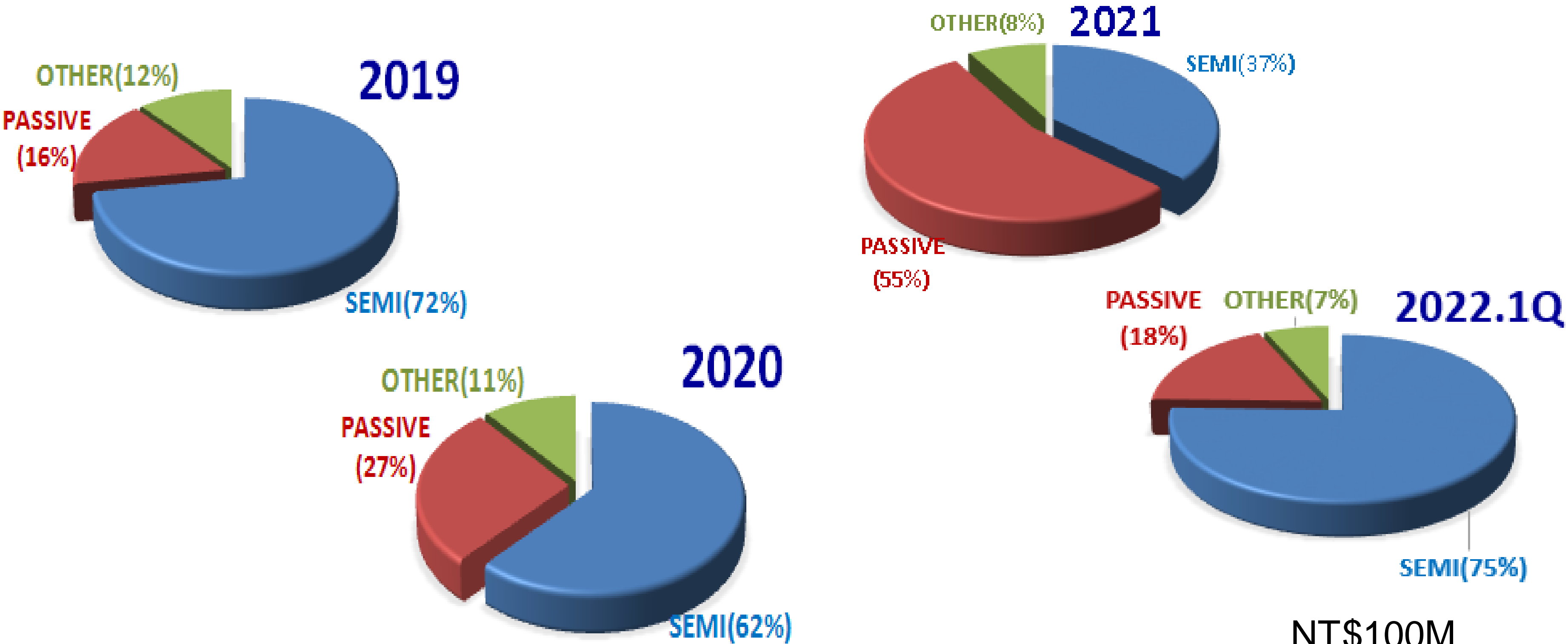
Passive Component Production Process



財務資料

	111.Q1		110.Q1	
營業收入	629,591		574,120	
營業成本	337,173		285,779	
營業毛利	292,418	47%	288,341	50%
推銷費用	16,604		21,113	
管理費用	36,075		32,771	
研究發展費用	90,810		75,118	
預期信用減損損失	5,217		469	
營業費用合計	148,706	24%	129,471	22%
營業利益	143,712		158,870	
營業外收入及支出	35,431		2,093	
稅前淨利	179,143	28%	160,963	28%
所得稅費用	30,025		27,490	
本期淨利	149,118	23%	133,473	23%
EPS	1.83		1.64	

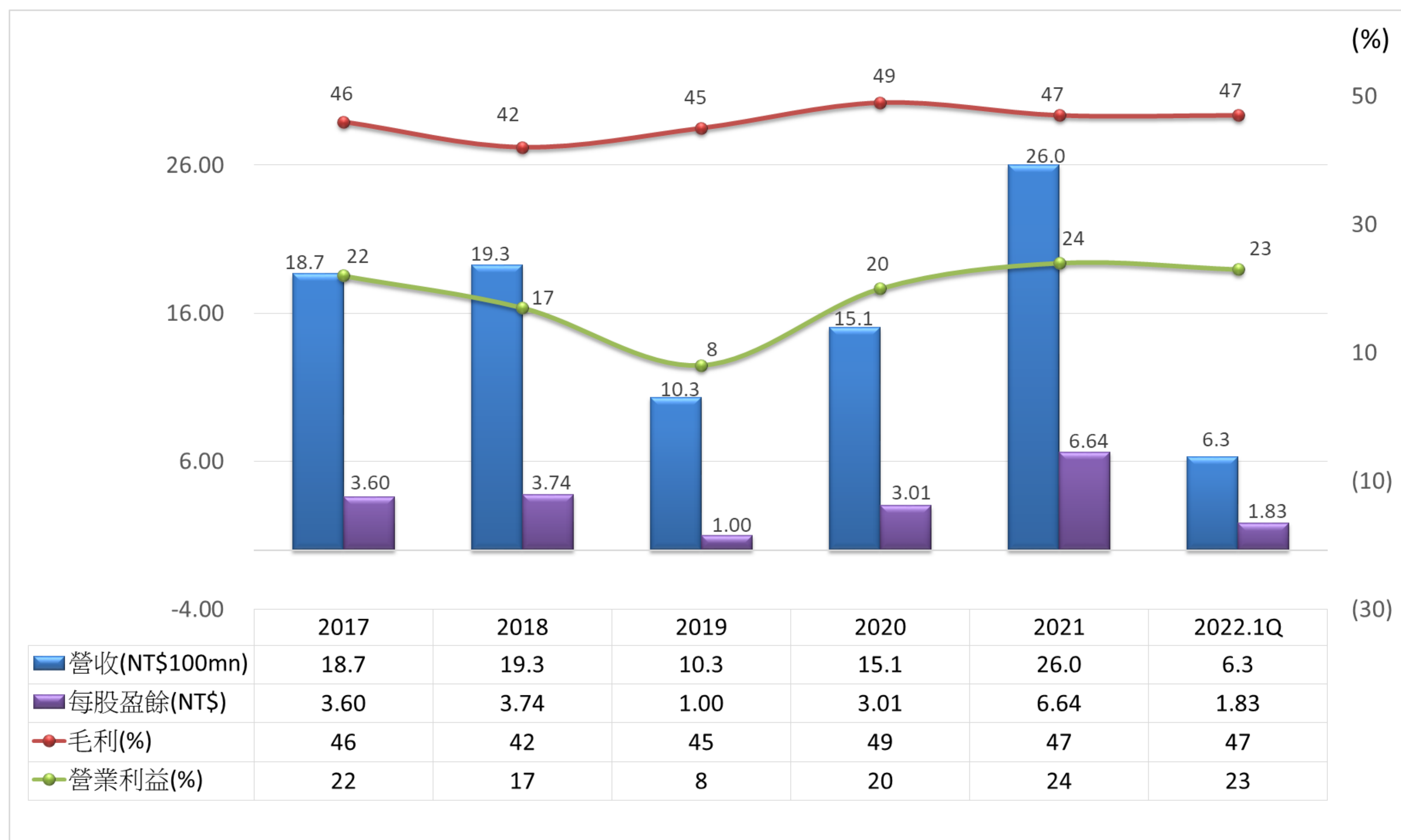
Revenue Breakdown



NT$100M

	2019		2020		2021		2022.1Q	
SEMI	7.48	72%	9.28	62%	9.60	37%	4.75	75%
PASSIVE	1.70	16%	4.14	27%	14.29	55%	1.13	18%
OTHER	1.14	12%	1.64	11%	2.15	8%	0.42	7%
TOTAL	10.32	100%	15.06	100%	26.04	100%	6.30	100%

Financial Highlights



	2017	2018	2019	2020	2021	2022.1Q
營收(NT$100mn)	18.7	19.3	10.3	15.1	26.0	6.3
每股盈餘(NT$)	3.60	3.74	1.00	3.01	6.64	1.83
毛利(%)	46	42	45	49	47	47
營業利益(%)	22	17	8	20	24	23

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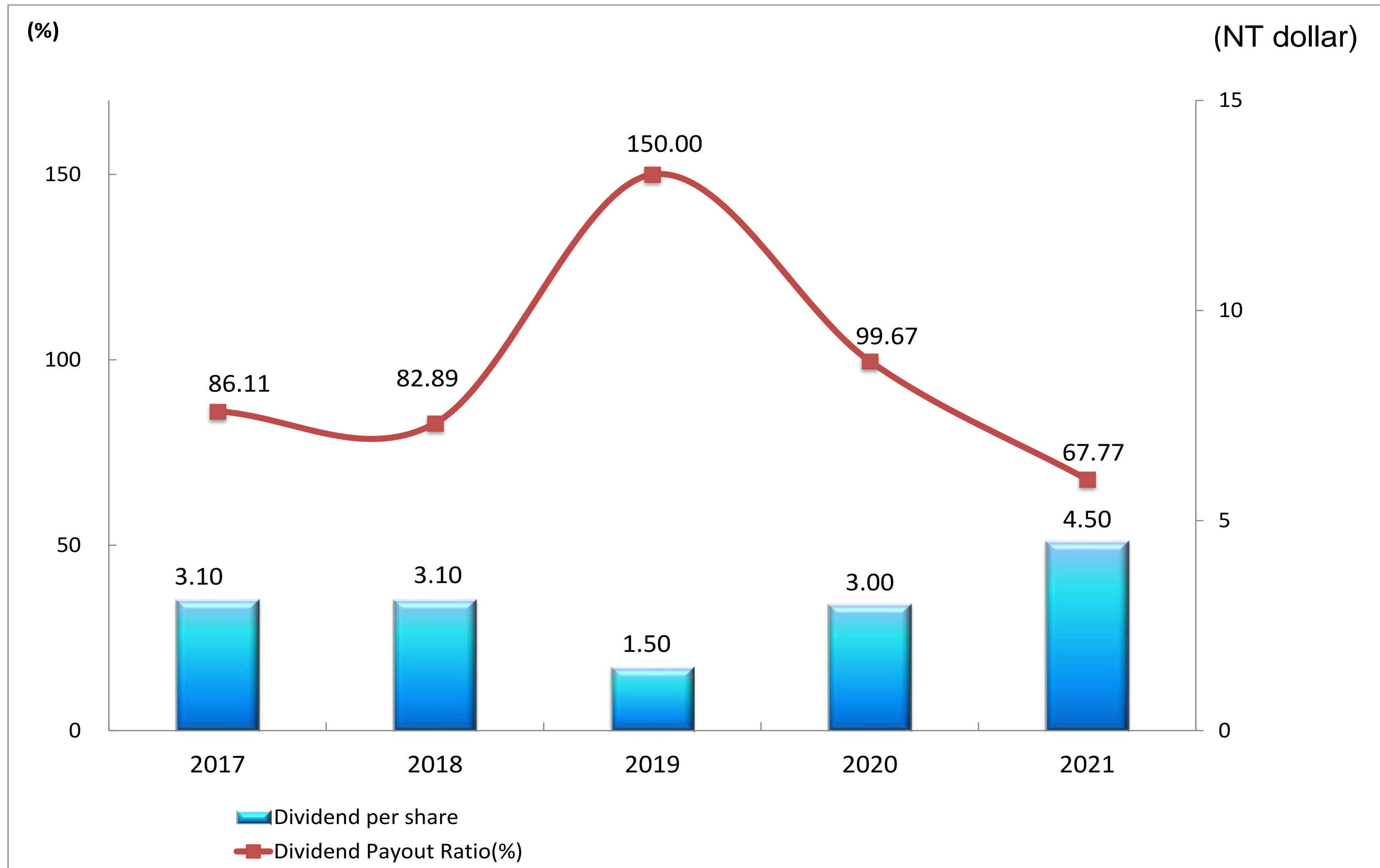

Thank you!